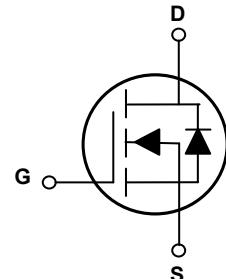


Main Product Characteristics

$V_{(BR)DSS}$	100V
$R_{DS(ON)}$	84mΩ (typ.)
I_D	15A



PPAK3x3



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFN10110 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, @ Steady-State ($T_A=25^\circ\text{C}$) ¹	I_D	15	A
Continuous Drain Current, @ Steady-State ($T_A=100^\circ\text{C}$)		9.5	A
Pulsed Drain Current ²	I_{DM}	60	A
Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	34	W
Linear Derating Factor ($T_A=25^\circ\text{C}$)		0.19	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy ³	E_{AS}	11	mJ
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	4.4	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (PCB Mounted, Steady-State) ⁴	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	T_J/T_{STG}	-55 to +175	$^\circ\text{C}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	100	-	-	V
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$T_J=125^\circ\text{C}$	-	-	50	
Gate-to-Source Forward Leakage	I_{GSS}	$V_{\text{GS}}=20\text{V}$	-	-	100	nA
		$V_{\text{GS}}=-20\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=9\text{A}$	-	84	106	$\text{m}\Omega$
		$V_{\text{GS}}=6\text{V}, I_D=3\text{A}$	-	92	110	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	1.1	1.8	2.9	V
Forward Transconductance	g_{fs}	$V_{\text{DS}}=10\text{V}, I_D=5\text{A}$	-	15	-	S
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=1\text{MHz}$	-	446	-	pF
Output Capacitance	C_{oss}		-	57	-	
Reverse Transfer Capacitance	C_{rss}		-	2.8	-	
Total Gate Charge	Q_g	$I_D=10\text{A}, V_{\text{DS}}=50\text{V}, V_{\text{GS}}=10\text{V}$	-	8.2	-	nC
Gate-to-Source Charge	Q_{gs}		-	2.8	-	
Gate-to-Drain ("Miller") Charge	Q_{gd}		-	1.6	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, R_L=5\Omega, R_{\text{GEN}}=3\Omega$	-	2.6	-	nS
Rise Time	t_r		-	22	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	8.4	-	
Fall Time	t_f		-	12	-	
Gate Resistance	R_g	$f=1\text{MHz}$	-	1.4	-	Ω
Source-Drain Ratings and Characteristics						
Continuous Source Current (Body Diode)	I_s	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	15	A
Pulsed Source Current (Body Diode)	I_{SM}		-	-	60	A
Diode Forward Voltage	V_{SD}	$I_s=10\text{A}, V_{\text{GS}}=0\text{V}$	-	1	1.3	V
Reverse Recovery Time	T_{rr}	$I_s=10\text{A}, V_{\text{GS}}=0\text{V}, dI_F/dt=100\text{A}/\mu\text{s}$	-	46	-	nS
Reverse Recovery Charge	Q_{rr}		-	40	-	nC

Notes:

1. Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. $L=0.5\text{mH}$, $R_G=25\Omega$, $V_{\text{DD}}=80\text{V}$, $I_{\text{AS}}=6.5\text{A}$, $T_J=25^\circ\text{C}$.
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Electrical and Thermal Characteristic Curves

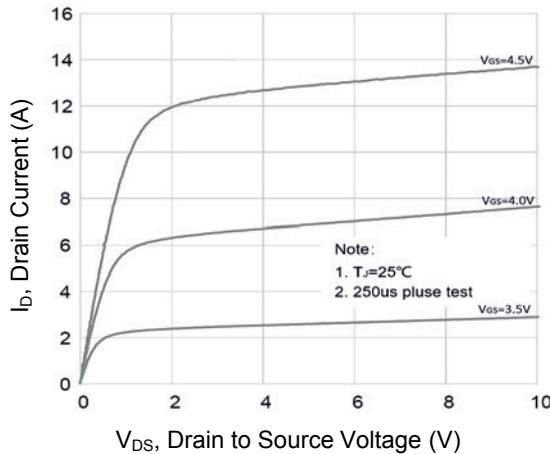


Figure 1. Typical Output Characteristics

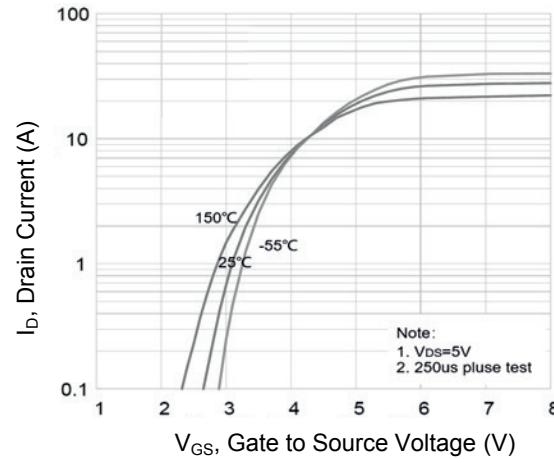


Figure 2. Transfer Characteristics

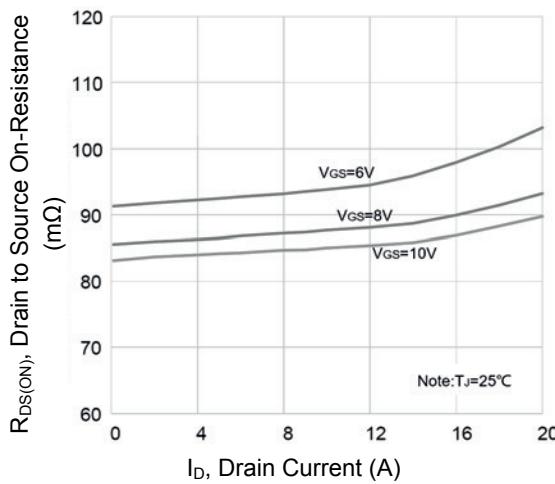


Figure 3. $R_{DS(ON)}$ vs. Drain Current

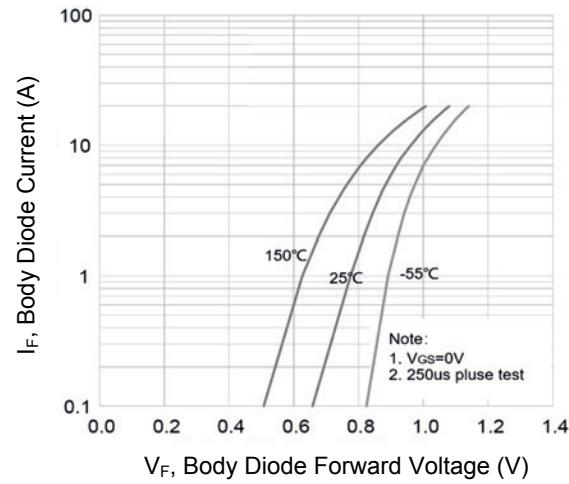


Figure 4. Body Diode Characteristics

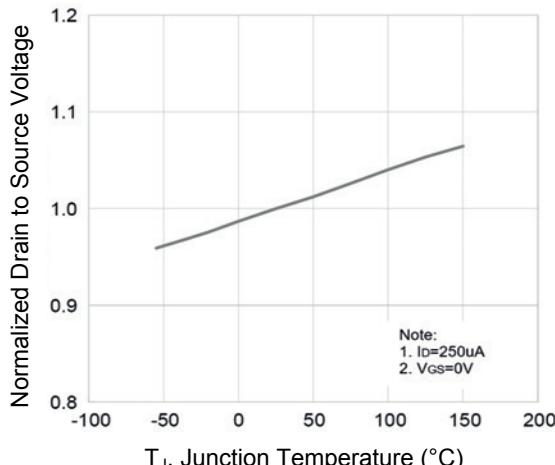


Figure 5. Normalized BV_{DSS} vs. T_J

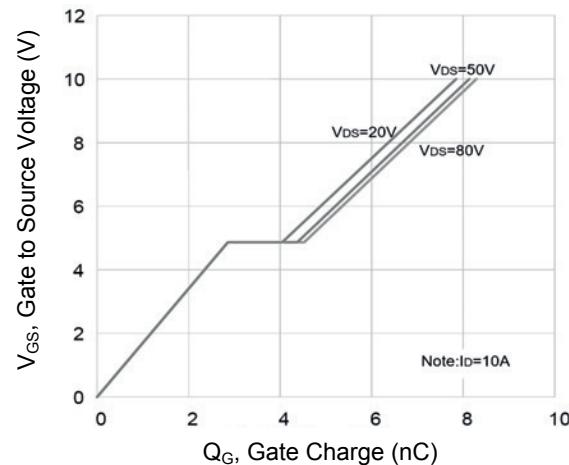


Figure 6. Gate Charge

Typical Electrical and Thermal Characteristic Curves

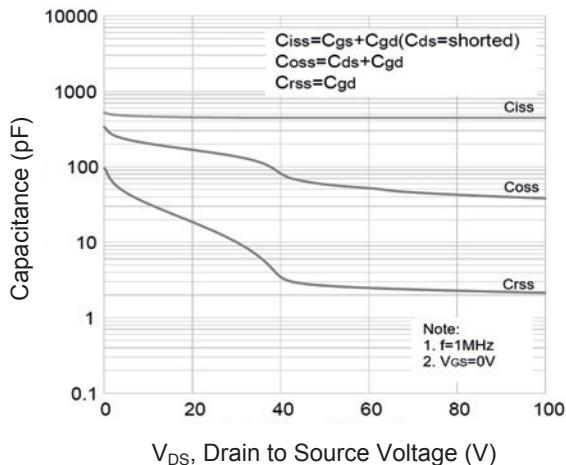


Figure 7. Capacitance Characteristics

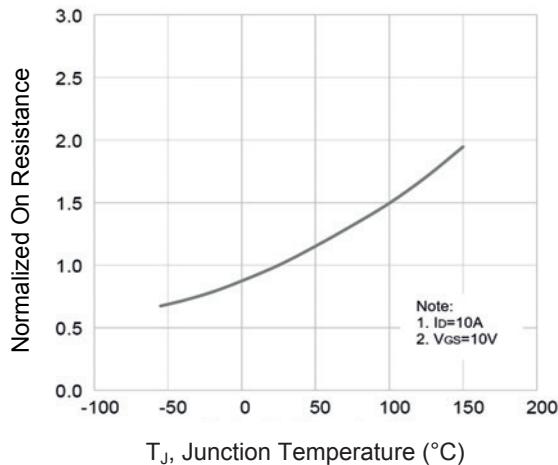


Figure 8. Normalized $R_{DS(ON)}$ vs. T_J

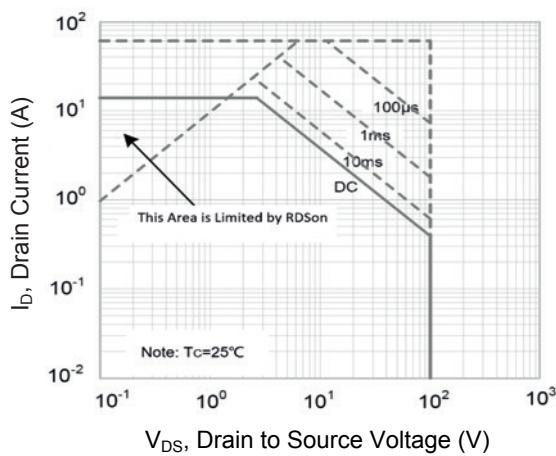
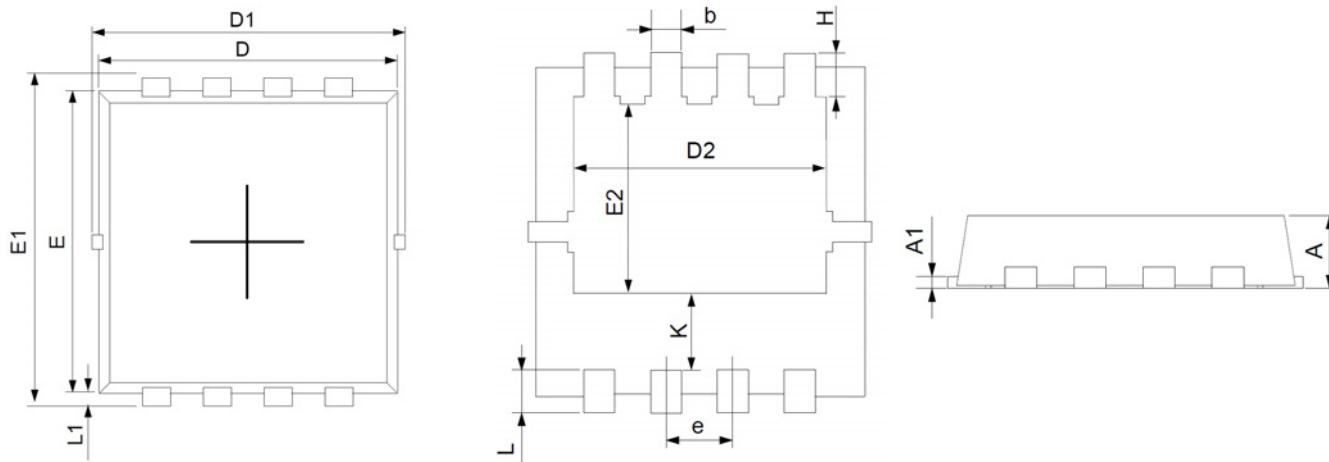


Figure 9. Safe Operation Area

Package Outline Dimensions (PPAK3x3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.70	0.90	0.028	0.035
A1	0.14	0.20	0.006	0.008
D	3.05	3.25	0.120	0.128
E	2.90	3.10	0.114	0.122
D1	3.10	3.50	0.122	0.138
D2	2.35	2.50	0.093	0.098
E1	3.10	3.50	0.122	0.138
E2	1.64	1.84	0.065	0.072
b	0.25	0.35	0.010	0.014
K	0.59	0.79	0.023	0.031
e	0.55	0.75	0.022	0.030
L	0.25	0.55	0.010	0.022
L1	0.10	0.20	0.004	0.008
H	0.32	0.52	0.013	0.020

Order Information

Device	Package	Marking	Carrier	Quantity
GSFN10110	PPAK3x3	N10110	Tape & Reel	5,000 pcs / Reel